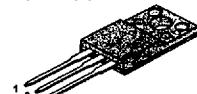


**FEATURES**

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25  $\mu$ A (Max.) @  $V_{DS} = 800V$
- Low  $R_{DS(on)}$  : 3.800  $\Omega$  (Typ.)

$BV_{DSS} = 800\text{ V}$   
 $R_{DS(on)} = 4.8\ \Omega$   
 $I_D = 2\text{ A}$

**TO-220F**

1.Gate 2.Drain 3.Source

**Absolute Maximum Ratings**

Symbol	Characteristic	Value	Units
$V_{DSS}$	Drain-to-Source Voltage	800	V
$I_D$	Continuous Drain Current ( $T_c=25\text{ }^\circ\text{C}$ )	2	A
	Continuous Drain Current ( $T_c=100\text{ }^\circ\text{C}$ )	1.3	
$I_{DM}$	Drain Current-Pulsed ①	12	A
$V_{GS}$	Gate-to-Source Voltage	+30	V
$E_{AS}$	Single Pulsed Avalanche Energy ②	235	mJ
$I_{AR}$	Avalanche Current ①	2	A
$E_{AR}$	Repetitive Avalanche Energy ①	3.5	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	2.0	V/ns
$P_D$	Total Power Dissipation ( $T_A=25\text{ }^\circ\text{C}$ ) *	35	W
	Total Power Dissipation ( $T_c=25\text{ }^\circ\text{C}$ )	0.28	W
	Linear Derating Factor		W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

**Thermal Resistance**

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	3.57	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

**SAMSUNG**  
ELECTRONICS

# SSS3N80A

N-CHANNEL  
POWER MOSFET

## Electrical Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	800	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	1.01	--	V/ $^\circ\text{C}$	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	--	3.5	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage , Forward	--	--	100	nA	$\text{V}_{\text{GS}}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100	nA	$\text{V}_{\text{GS}}=-30\text{V}$
$\text{I}_{\text{DSS}}$	Drain-to-Source Leakage Current	--	--	25	$\mu\text{A}$	$\text{V}_{\text{DS}}=800\text{V}$
		--	--	250		$\text{V}_{\text{DS}}=640\text{V}, \text{T}_c=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	4.8	$\Omega$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=0.85\text{A}$ ④*
$\text{g}_{\text{fs}}$	Forward Transconductance	--	1.78	--	$\text{mS}$	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=0.85\text{A}$ ④
$\text{C}_{\text{iss}}$	Input Capacitance	--	580	750	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
$\text{C}_{\text{oss}}$	Output Capacitance	--	60	75		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance	--	23	30		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	16	40	ns	$\text{V}_{\text{DD}}=400\text{V}, \text{I}_D=2\text{A},$ $\text{R}_G=16\Omega$ See Fig 13 ④ ⑤
$t_r$	Rise Time	--	26	60		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	46	100		
$t_f$	Fall Time	--	24	60		
$\text{Q}_g$	Total Gate Charge	--	27	35	nC	$\text{V}_{\text{DS}}=640\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_D=2\text{A}$ See Fig 6 & Fig 12 ④ ⑤
$\text{Q}_{\text{gs}}$	Gate-Source Charge	--	5.3	--		
$\text{Q}_{\text{gd}}$	Gate-Drain("Miller") Charge	--	12.2	--		

## Source-Drain Diode Ratings and Characteristics

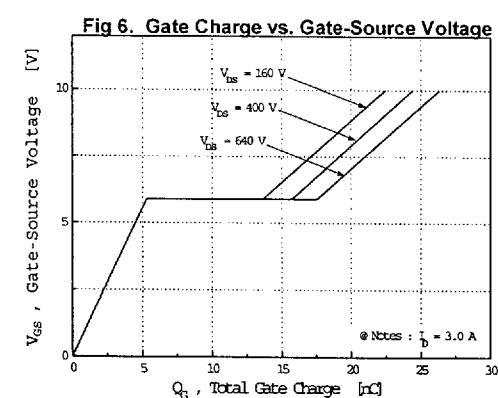
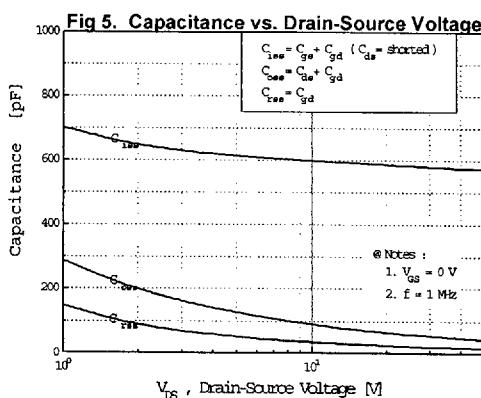
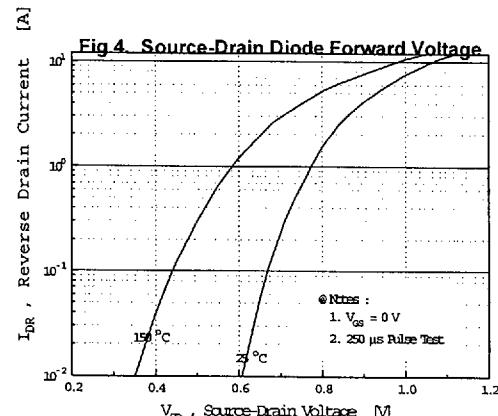
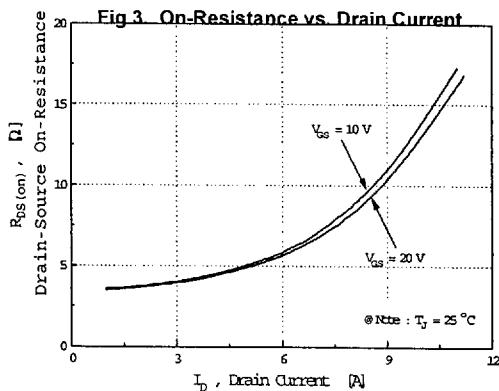
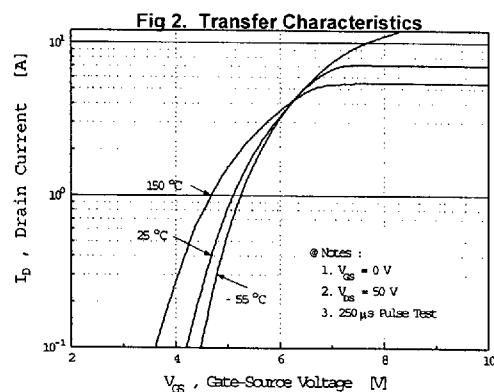
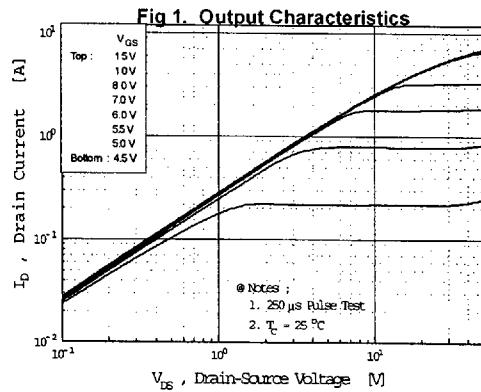
Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{I}_s$	Continuous Source Current	--	--	2	A	Integral reverse pn-diode in the MOSFET
$\text{I}_{\text{SM}}$	Pulsed-Source Current ①	--	--	12	A	
$\text{V}_{\text{SD}}$	Diode Forward Voltage ④	--	--	1.4	V	$\text{T}_J=25^\circ\text{C}, \text{I}_s=2\text{A}, \text{V}_{\text{GS}}=0\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time	--	330	--	ns	$\text{T}_J=25^\circ\text{C}, \text{I}_F=3\text{A}$
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge	--	1.52	--	$\mu\text{C}$	$d\text{I}/dt=100\text{A}/\mu\text{s}$ ④

### Notes :

- Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- $L=110\text{mH}, \text{I}_{\text{AS}}=2\text{A}, \text{V}_{\text{DD}}=50\text{V}, \text{R}_G=27\Omega$ , Starting  $\text{T}_J=25^\circ\text{C}$
- $\text{I}_{\text{SD}} \leq 3\text{A}, d\text{I}/dt \leq 100\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $\text{T}_J=25^\circ\text{C}$
- Pulse Test : Pulse Width =  $250\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- Essentially Independent of Operating Temperature

N-CHANNEL  
POWER MOSFET

**SSS3N80A**



# SSS3N80A

N-CHANNEL  
POWER MOSFET

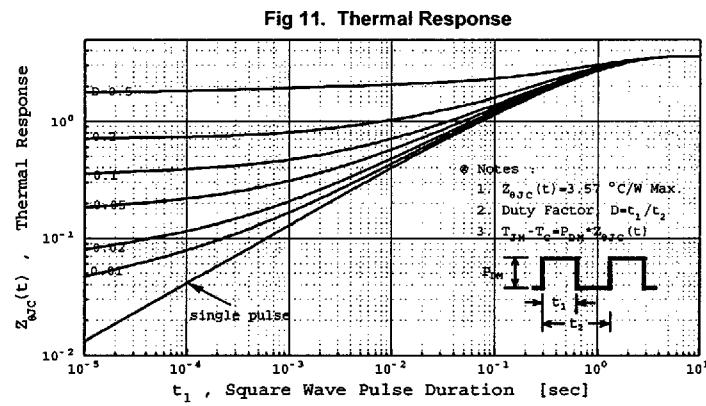
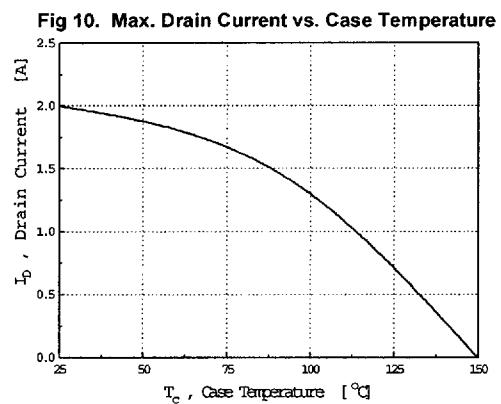
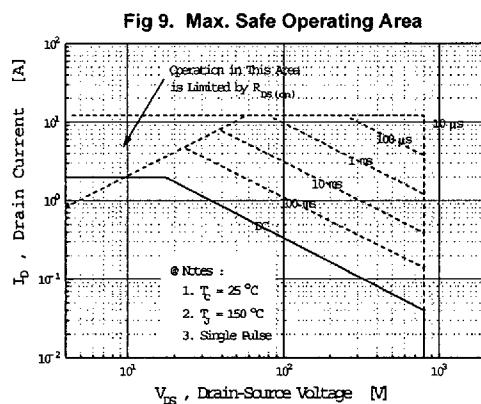
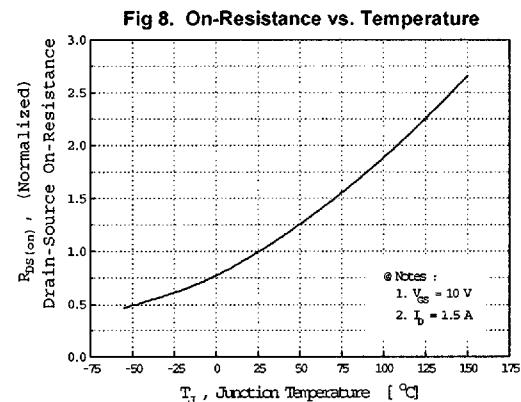
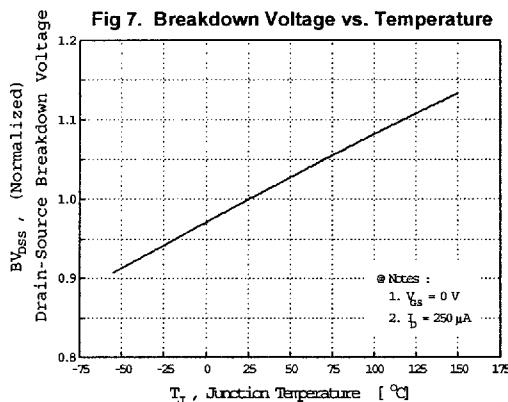


Fig 12. Gate Charge Test Circuit & Waveform

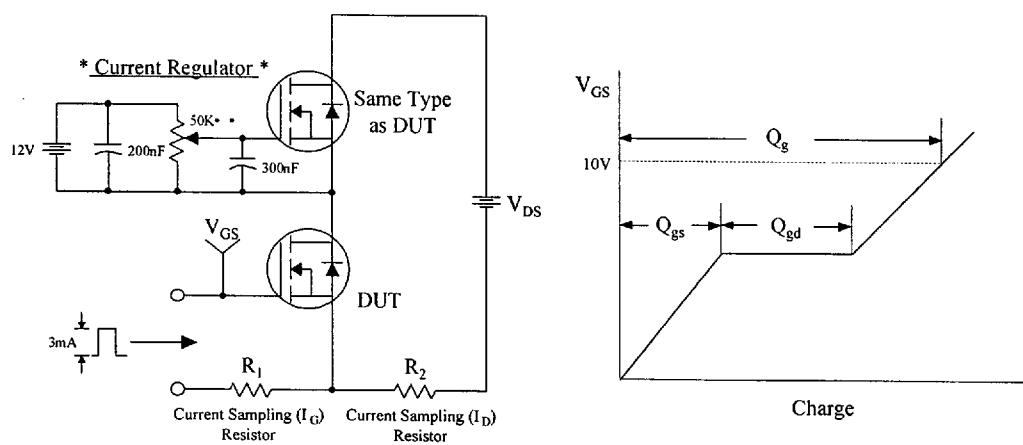


Fig 13. Resistive Switching Test Circuit & Waveforms

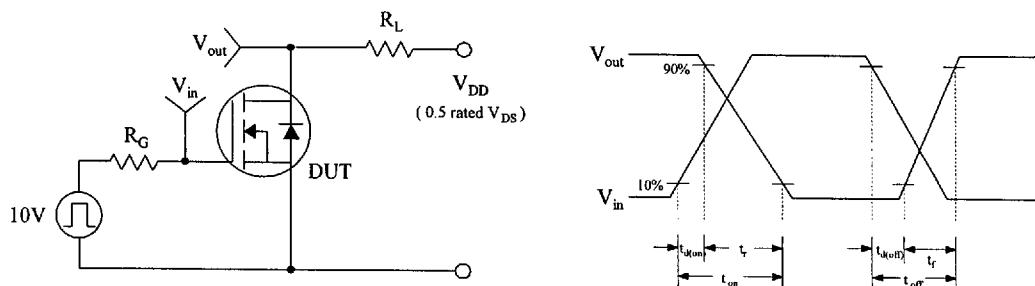
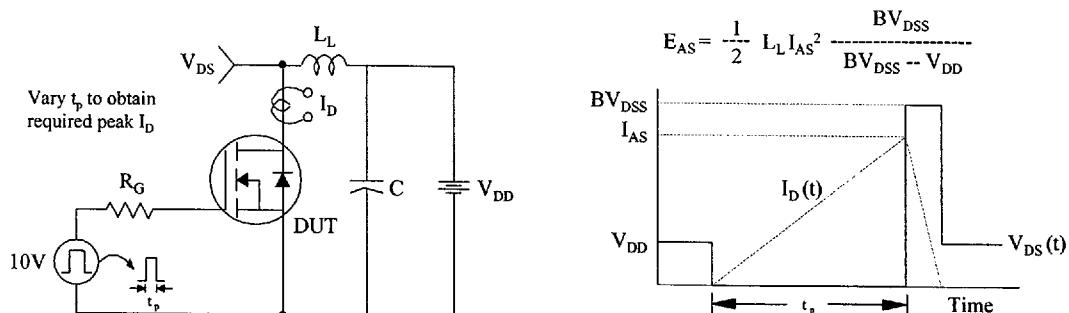


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

